

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A multi-chip module comprising:

a plurality of first semiconductor chips surface-mounted on a surface of a mounting board ~~for~~ exchanging to exchange signals with each other;

a plurality of bumps that electrically couple said plurality of first semiconductor chips with said mounting board;

a second semiconductor chip mounted back-to-back with at least one of said plurality of first semiconductor chips, said second semiconductor chip having ~~most~~ a plurality of bonding pads on a front surface thereof, a majority of said bonding pads being ~~thereof~~ arranged along one side ~~thereof~~ of said front surface;

a plurality of bonding wires ~~for connecting coupling~~ the bonding pads of said second semiconductor chip and with corresponding electrodes formed on said mounting board; and

a sealing member ~~for~~ encapsulating said plurality of first semiconductor chips, said second semiconductor chip, and the said bonding ~~wire~~ wires, on said mounting board.

2. (Currently Amended) A multi-chip module according to claim 1,

wherein said plurality of first semiconductor chips include a microcomputer chip, a random access memory chip, and a signal processing ~~device for processing~~ chip adapted to process signals for specific applications, respectively; and

wherein said second semiconductor chip is a nonvolatile memory chip.

3. (Currently Amended) A multi-chip module according to claim 2,

wherein said microcomputer chip is coupled to one of and said random access memory [[or]] chip and said signal processing chip device for processing the signal for specified applications which is connected to said ~~microcomputer are interconnected by wiring of said formed on~~ the mounting board ~~by imposition~~; and

wherein said microcomputer chip includes an, exclusive interface corresponding to said nonvolatile memory chip,

said microcomputer chip and said nonvolatile memory chip being interconnected through said bonding wire wires.

4. (Currently Amended) A multi-chip module according to claim 3,

wherein said at least one of said plurality of first semiconductor chips mounted back-to-back with said nonvolatile memory chip includes at least is mounted back-to-back with said microcomputer chip first semiconductor chips including said microcomputer.

5. (Currently Amended) A multi-chip module according to claim 4,

wherein said at least one of said plurality of first semiconductor chips mounted back-to-back with said nonvolatile memory chip further includes include said microcomputer and said random access memory chip; and

wherein ~~the a long side of the semiconductor chip constituting said random access memory chip and the a long side of the semiconductor chip constituting said nonvolatile memory chip are arranged orthogonally with respect to each other.~~